

#4/Pre-Amdt A/
Sub Spec (N.G.)
10/25/81
D King

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Charles W.C. Lin
Title: BUMPLESS FLIP CHIP ASSEMBLY WITH SOLDER VIA
Serial No.: Unknown Filed: Herewith
Examiner: Unknown Group Art Unit: Unknown
Atty. Docket No.: P002-2

ASSISTANT COMMISSIONER FOR PATENTS
Washington, D.C. 20231

PRELIMINARY AMENDMENT

Dear Sir:

Please amend the application as follows.

In the Abstract and Specification

Replace the Abstract and Specification with the enclosed Substitute Specification.

In the Claims

Cancel claims 1-14 without prejudice or disclaimer to the subject matter recited therein.

Add the following claims: